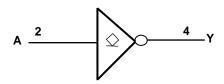


Pin Descriptions

Pin Name	Description			
NC	No connection			
А	Data Input			
GND	Ground			
Υ	Data Output Open Drain			
Vcc	Supply Voltage			

Logic Diagram



Function Table

Inputs	Output
Α	Υ
Н	L
L	Z



Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to 6.5	V
Vı	Input Voltage Range	-0.5 to 6.5	V
V _o	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
V _o	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 4)

Symbol		Parameter	Min	Max	Unit
\/	Operating Voltage	Operating	1.4	5.5	V
V _{cc}	Operating Voltage	Data retention only	1.2		V
		V _{CC} = 1.4 V to 1.95 V	0.65 X V _{CC}		
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	High lovel Input Voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
V _{IH}	High-level Input Voltage	V _{CC} = 3 V to 3.6 V	2		V
		V _{CC} = 4.5 V to 5.5 V	0.7 X V _{CC}		
	Low-level input voltage	V _{CC} = 1.4 V to 1.95 V		0.35 X V _{CC}	
		V _{CC} = 2.3 V to 2.7 V		0.7	V
V _{IL}		V _{CC} = 3 V to 3.6 V		0.8	V
		V _{CC} = 4.5 V to 5.5 V		0.3 X V _{CC}	
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	V _{CC}	V
		Vcc=1.4 V		3	
		V _{CC} = 1.65 V		4	
	Lavelaval avitavit avimost	V _{CC} = 2.3 V		8	A
I _{OL}	Low-level output current			16	mA
		$V_{CC} = 3 V$		24	
		V _{CC} = 4.5 V		32	
		V _{CC} = 1.4 V to 3.0 V		20	
Δt/ΔV	Input transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V		10	ns/V
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5	
T _A	Operating free-air temperature		-40	85	°C

Notes: 4. Unused inputs should be held at Vcc or Ground.



Electrical Characteristics (All typical values are at Vcc = 3.3V, T_A = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Max	Unit
		I _{OL} = 100 μA	1.4 V to 5.5 V			0.1	
		I _{OL} = 3 mA	1.4 V			0.4	
		I _{OL} = 4 mA	1.65 V			0.45	
V_{OL}	Low Level Output Voltage	I _{OL} = 8 mA	2.3 V			0.3	V
	Catput Voltago	I _{OL} = 16 mA	3 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
		I _{OL} = 32 mA	4.5 V			0.55	
l _l	Input Current	V _I = 5.5 V or GND	0 to 5.5 V			± 5	μΑ
l _{oz}	Z State Leakage Current	V _O = 5.5V	3.6 V			± 10	μΑ
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 5.5V$	0 V			± 10	μΑ
I _{cc}	Supply Current	$V_1 = 5.5 \text{ V or GND } I_0 = 0$	1.4 V to 5.5 V			10	μΑ
ΔI_{CC}	Additional Supply Current	Input at V _{CC} –0.6 V	3 V to 5.5 V			500	μΑ
C _{li}	Input Capacitance	V _I = V _{CC} or GND	3.3V		4		pF
Co	Output Capacitance	V _O = V _{CC} or GND	3.3V		5		pF
		SOT25	(Note 5)		204		
θ_{JA}	Thermal Resistance Junction-to-Case	SOT353	(Note 5)		371		°C/W
	Carlotter to Case	DFN1410	(Note 5)		430		
		SOT25	(Note 5)		52		
θ_{JC}	Thermal Resistance Junction-to-Case	SOT353	(Note 5)		143		°C/W
		DFN1410	(Note 5)		190		

Notes: 5. Test condition for SOT25, SOT353, and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		3.3 V 3.3 V		= 5 V).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	А	Y	1.5	7.8	1	4.5	0.8	3.2	0.8	3.2	8.0	2.7	ns

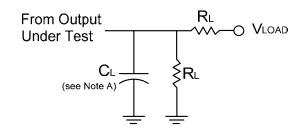
Operating Characteristics

 $T_A = 25$ °C

Pi	arameter		Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V	Vcc = 3.3 V	Vcc = 5 V	Unit
		Conditions	TYP	TYP	TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	f = 10 MHz	3	3	3	4	6	pF



Parameter Measurement Information



TEST	Condition
t _{PLZ} (see Notes D and E)	Vload
t _{PZL} (see Notes D and F)	Vload

Vcc	Inputs		V _M	V _{LOAD}	CL	RL	V Δ
	Vı	t _r /t _f	- 141	LOAD	o_		
1.8V±0.15V	V _{cc}	≤2ns	V _{cc} /2	2 X V _{CC}	30pF	1ΚΩ	0.15V
2.5V±0.2V	V _{cc}	≤2ns	V _{cc} /2	2 X V _{CC}	30pF	500Ω	0.15V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V _{cc}	≤2.5ns	V _{CC} /2	2 X V _{CC}	50pF	500Ω	0.3V

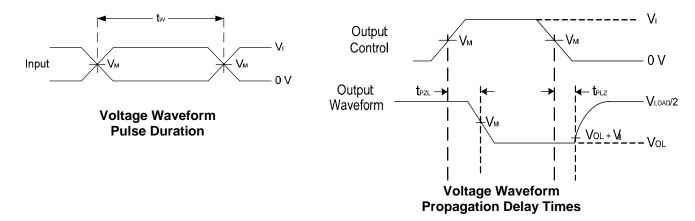


Figure 1. Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
- C. The inputs are measured one at a time with one transition per measurement. D. For the open drain device t_{PLZ} and t_{PZL} are the same as t_{PD}
- E. t_{PZL} is measured at V_{M} .
- F. t_{PLZ} is measured at $V_{OL} + V_{\Delta}$



Ordering Information

T4 LVCE1G 06 XXX - 7

Logic Device Function Package Packing

74 : Logic Prefix 06 : Inverter Buffer W5 : SOT25 7 : Tape & Reel

LVCE: 1.4 to 5.5V With Open Drain SE: SOT353
Family FZ4: DFN1410

1G: One gate

Device Package		Package Packaging		7" Tape and Reel		
Device	Code	(Note 6)	Quantity	Part Number Suffix		
74LVCE1G06W5-7	W5	SOT25	3000/Tape & Reel	-7		
74LVCE1G06SE-7	SE	SOT353	3000/Tape & Reel	-7		
74LVCE1G06FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7		

Notes: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Marking Information

(1) SOT25 and SOT353

(Top View)

4 XX Y WX

2

XX: Identification code

Y: Year 0~9

<u>W</u>: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents 52 and 53 week

X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G06W5	SOT25	PM
74LVCE1G06SE	SOT353	PM

(2) DFN1410

(Top View)

3

<u>XX</u> $\underline{Y}\underline{W}\underline{X}$ XX: Identification Code

Y: Year: 0~9

 \overline{W} : Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

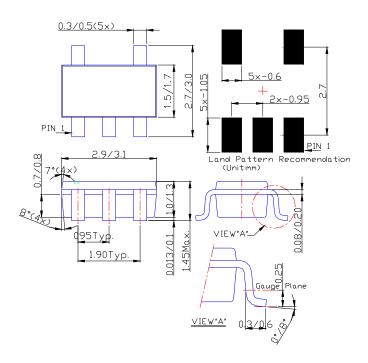
52 and 53 week X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G06FZ4	DFN1410	PM

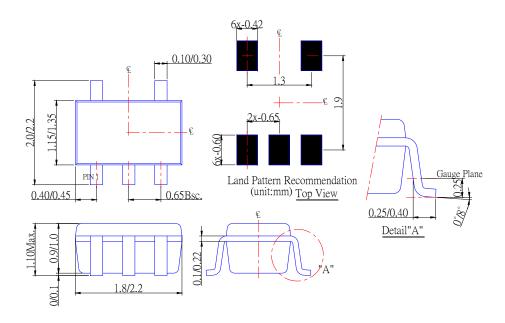


Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



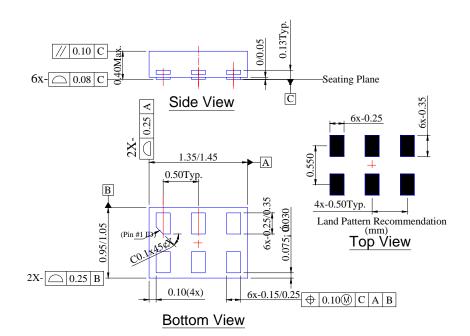
(2) Package Type: SOT353





Package Outline Dimensions (Continued)

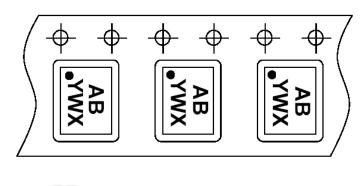
(3) Package Type: DFN1410

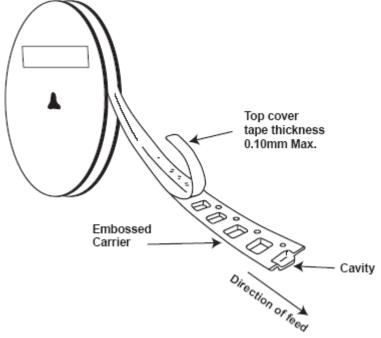




Taping Orientation (Note 7)

For DFN1410





Notes: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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